



42390.P11026

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Kloster, et. al.

Serial No.: 09/820,079

Filed: March 28, 2001

For: STRUCTURE IN A
MICROELECTRONIC DEVICE
INCLUDING A BI-LAYER FOR A
DIFFUSION BARRIER AND AN
ETCH STOP LAYER

Examiner: Thomas J. Magee

Group Art Unit: 2811

Attorney Docket No.: 42390.P11026

CERTIFICATE OF MAILING

I hereby certify that this paper or fee along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner of Patents and Trademarks, P.O. Box 1450, Alexandria, VA 22313-1450.

12-29-07
Date of Deposit

[Signature]
Signature of registered practitioner or other person
having reasonable basis to expect mailing to occur
on date of deposit shown pursuant to 37 C.F.R. §
1.8(a)(1)(ii)

DEREK S. WATSON
Typed/printed name of person whose signature is
contained above

RESPONSE AFTER FINAL REJECTION

Hon. Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

This response after final rejection is in response to the Final Office Action mailed October 31, 2003 and is submitted to put the pending case into condition for allowance thereof or into better condition for appeal. Consideration of this response is respectfully requested.

RECEIVED
JAN - 7 2004
TECHNOLOGY CENTER 2800